ASSOCIATION CONNECTIN ELECTRONICS INDUSTRIE	© Convright 2005 IPC Bannockburn Illinois All rights reserved under both				This document is a declaration of the substances within the manufacturer listed item. Note: if the item is an assembly with lower level parts, the declaration encompasses all lower level materials for which the manufacturer has engineering responsibility.										
1752-21.1	IPC Web Site for Information on IPC-1752 Standard Form Typ http://www.ipc.org/IPC-175x Distribute				e *	* Declaration Class * Class 6 - RoHS Yes/No, Homogeneous Materi				als and Mfg Information					
Supplier Inform	ation														
Company name* C			Company unique ID			Unique ID Authority				Response Date*					
onsemi											2024-04-26				
Contact Name 7			Title - Contact				Phone - Contact*				Email -	Email - Contact*			
Product-Env-Stewards			Product Enviro Compliance				NA				Product-Env-Stewards@onsemi.com				
Authorized Representative* T			Title - Representative				Phone - Representative*				Email - Representative*				
Product-Env-Stewards			Product Enviro Compliance				NA				Product-Env-Stewards@onsemi.com				
Requeste	Requester Item Number Mfr Item		Number Mfr Item Name				Effective Date	Date Version Manufacturing Site			Weight*	UOM	Unit Type		
		FDMS86	DMS86104 FET 100V 24.0		mOhm PQFN56		2024-04-26	-04-26		CNJ		105.957	mg	Each	
Manufacturing	Proccess Information	1													
Terminal Plating / Grid Array Material Termin			erminal Base A	nal Base Alloy J-STD-020 MSL R			Peak Process Body Temperature Max Time at Peak			Temperature Number of Reflow Cycles					
Matte Tin (Sn) - annealed CU Allo			CU Alloy	1			260 C 30		30	seconds 3					
Comments															
evel 1 - maximum t	ime at peak temperature o	luring sol	dering is 10-3	0 seconds											
For more informati	on regarding material con	position	please refer to	page 3											

RoHS Material Composition Declaration				Declaration Type *	Detailed				
Directive 2015/863/EU amending RoHS Directive 2011/65/EU		mium (Cr6+), Polybrominated Biphenyls (Pl		dmium and quantity limit of 0.1% by mass (10 minated Diphenyl Ethers (PBDE), and Bis(2-et					
cadmium, hexavalentchromium, polybromina contains a RoHS restricted substance inexces encompass all such components. Supplier cer as of the date that Supplier completes this for Company acknowledges that Supplier may h independently verified information provided certification in this paragraph. If the Company	ated biphenyls and/or polybrominated dip s of an applicable quantity limit, please in iffies that it gathered the information it pr m.Supplier acknowledges that Company ave relied on informationprovided by oth by others, Supplier agrees that, at a minir and the Supplier enter into a written agr esource of the Supplier's liability and the	henyl ethers (each a "RoHS restricted substa ndicate below which, if any, RoHS exemption ovides in this form using appropriate methoo will rely on this certification in determining ers in completing this form, and that Supplie num, itssuppliers have provided certification eement with respect to the identified part, the Company's remedies for issues that arise reg	nce") in exco n you believe ls to ensure i the compliar r may not ha s regarding t terms and co	e may apply. If the part is an assembly with low s accuracy and that such information is true an ce of its products with European Union member de independently verified such information. Ho neir contributions to the part, and those certifica	ove. If a homogeneous material within the part er level components, the declaration shall d correct to the best of its knowledge and belief, er state laws that implement the RoHS Directive. wever, in situations where Supplier has not ations are at least as comprehensive as the anty rights and/or remedies provided as part of				
RoHS Declaration * 4 - Item(s) does not contain RoHS restricted subst	ances per the definition above except for sele	ected exempt	ions Supplier Acceptance	* Accepted				
Exemption: 7a: Lead in high melting temp	erature type solders (i.e. lead based sol	der alloys containing 85% by weight or m	ore lead).						
Exemption List Version	EL-2011/534/EU								
Declaration Signature									
Instructions: Complete all of the required fields on all pages of this form. Select the "Accepted" on the Supplier Acceptance drop-down. This will display the signature area. Digitally sign the declaration (if required by the Requester) and click on Submit Form to have the form returned to the Requester.									
Supplier Digital Signature	astislav Drska	Le							

Homogeneous Material Composition Declaration for Electronic Products

SubItem Instructions: The presence of any JIG Level A or B substances must be declared. [1] indicate the subpart in which the substance is located, [2] provide a description of the homogeneous material [3], enter the weight of the homogeneous material.

Substance Instructions: [A] select the Level (JIG A, JIG B, Requester or Supplier) [B] select the substance category (JIG or Requester) or enter a value (Supplier). [C] select the substance (JIG) or enter the substance and CAS (Other). [D] select a RoHS exemption, if applicable [E] enter the weight of the substance or the PPM concentration [F] Optionally enter the positive (+) and negative (-) tolerance in percent (Note: percent tolerance values are expected to cover a 3

sigma range of distribution unless otherwise noted).									
Homogeneous Material	Weight	Unit of Measure	Level	Substance	CAS	Exempt	Weight	Unit of Measure	
Die	5.09	mg	Supplier	Silicon (Si)	7440-21-3		5.09	mg	
Die Attach Solder	6.941	mg	Supplier	Silver (Ag)	7440-22-4		0.1735	mg	
			А	Lead (Pb)	7439-92-1	7a	6.4204	mg	
			Supplier	Tin (Sn)	7440-31-5		0.3471	mg	
Lead Frame	35.434	mg	Supplier	Silver (Ag)	7440-22-4		0.038	mg	
			Supplier	Zinc (Zn)	7440-66-6		0.046	mg	
			Supplier	Iron (Fe)	7439-89-6		0.85	mg	
			Supplier	Copper (Cu)	7440-50-8		34.5	mg	
Mold Compound-Black	44.401	mg		Proprietary	proprietary data		3.5521	mg	
			Supplier	Carbon Black (C)	1333-86-4		0.222	mg	
			Supplier	Fused Silica (SiO2)	60676-86-0		40.6269	mg	
Plating	13.5	mg	Supplier	Tin (Sn)	7440-31-5		13.5	mg	
Wire Bond - Cu	0.591	mg	Supplier	Copper (Cu)	7440-50-8		0.591	mg	